



Material Content Data Sheet



Sales Product Name		BGA 925L6 E6327		Issued		25. September 2017		
MA#		MA000962774						
Package		PG-TSLP-6-2		Weight*		0.78 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.214	27.44	27.44	274351	274351
bumps	non noble metal	copper	7440-50-8	0.033	4.26	4.26	42645	42645
leadframe	non noble metal	nickel	7440-02-0	0.173	22.20	22.20	221971	221971
encapsulation	organic material	carbon black	1333-86-4	0.002	0.21		2100	
	plastics	epoxy resin	-	0.048	6.09		60895	
	inorganic material	silicondioxide	60676-86-0	0.279	35.68	41.98	356969	419964
leadfinish	noble metal	gold	7440-57-5	0.009	1.19	1.19	11861	11861
plating	noble metal	silver	7440-22-4	0.015	1.94	1.94	19368	19368
ubm	non noble metal	copper	7440-50-8	0.000	0.02		159	
	non noble metal	titanium	7440-32-6	0.000	0.01		56	
	non noble metal	tungsten	7440-33-7	0.000	0.00	0.03	29	244
solder	noble metal	silver	7440-22-4	0.000	0.02		220	
	non noble metal	tin	7440-31-5	0.007	0.94	0.96	9376	9596
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com